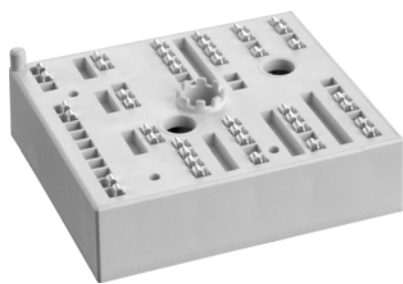


SKiiP 24NAB12T4V1



MiniSKiiP® 2

SKiiP 24NAB12T4V1

Features

- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

Typical Applications*

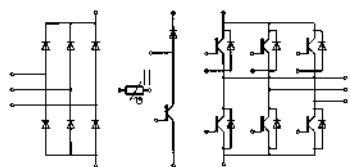
- Inverter up to 22 kVA
- Typical motor power 11 kW

Remarks

- Case temp. limited to $T_C = 125^\circ\text{C}$ max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)

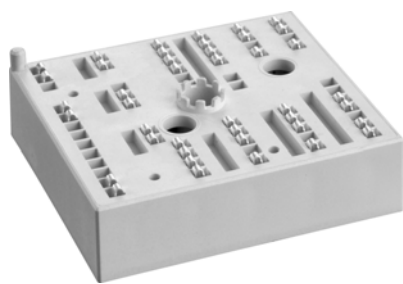
Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	48	A
	T _j = 175 °C	T _s = 70 °C	39	A
I _C	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	53	A
	T _j = 175 °C	T _s = 70 °C	44	A
I _{Cnom}			35	A
I _{CRM}	I _{CRM} = 3 x I _{Cnom}		105	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 800 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 150 °C	10	μs
T _j			-40 ... 175	°C
Chopper - IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	48	A
	T _j = 175 °C	T _s = 70 °C	39	A
I _C	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	53	A
	T _j = 175 °C	T _s = 70 °C	44	A
I _{Cnom}			35	A
I _{CRM}	I _{CRM} = 3 x I _{Cnom}		105	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 800 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 150 °C	10	μs
T _j			-40 ... 175	°C
Inverse - Diode				
V _{RRM}	T _j = 25 °C		1200	V
I _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	44	A
	T _j = 175 °C	T _s = 70 °C	35	A
I _F	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	49	A
	T _j = 175 °C	T _s = 70 °C	40	A
I _{Fnom}			35	A
I _{FRM}	I _{FRM} = 3 x I _{Fnom}		105	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 150 °C		170	A
T _j			-40 ... 175	°C
Freewheeling - Diode				
V _{RRM}	T _j = 25 °C		1200	V
I _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	44	A
	T _j = 175 °C	T _s = 70 °C	35	A
I _F	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	49	A
	T _j = 175 °C	T _s = 70 °C	40	A
I _{Fnom}			35	A
I _{FRM}	I _{FRM} = 3 x I _{Fnom}		105	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 150 °C		170	A
T _i			-40 ... 175	°C



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SKiiP 24NAB12T4V1



MiniSKiiP® 2

SKiiP 24NAB12T4V1

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- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

Typical Applications*

- Inverter up to 22 kVA
- Typical motor power 11 kW

Remarks

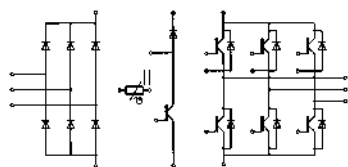
- Case temp. limited to $T_C = 125^\circ\text{C}$ max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)

Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Rectifier - Diode				
V _{RRM}	T _j = 25 °C		1600	V
I _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	52	A
	T _j = 150 °C	T _s = 70 °C	39	A
I _F	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	57	A
	T _j = 150 °C	T _s = 70 °C	43	A
I _{Fnom}			13	A
I _{FSM}	10 ms	T _j = 25 °C	370	A
	sin 180°	T _j = 150 °C	270	A
I ² t	10 ms	T _j = 25 °C	685	A ² s
	sin 180°	T _j = 150 °C	365	A ² s
T _j			-40 ... 150	°C
Module				
I _{t(RMS)}	T _{terminal} = 80 °C, 20 A per spring		40	A
T _{stg}			-40 ... 125	°C
V _{isol}	AC sinus 50 Hz, 1 min		2500	V

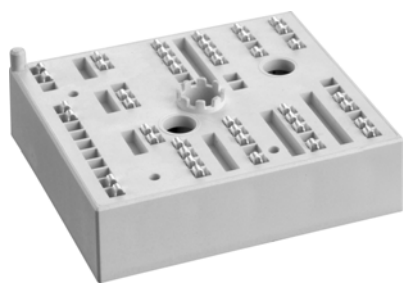
Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
Inverter - IGBT					
$V_{CE(sat)}$	$I_C = 35 \text{ A}$ $V_{GE} = 15 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.85	2.10	V
		$T_j = 150^\circ\text{C}$	2.25	2.45	V
V_{CE0}	chipelevel	$T_j = 25^\circ\text{C}$	0.80	0.90	V
		$T_j = 150^\circ\text{C}$	0.70	0.80	V
r_{CE}	$V_{GE} = 15 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	30	34	mΩ
		$T_j = 150^\circ\text{C}$	44	47	mΩ
$V_{GE(th)}$	$V_{GE} = V_{CE} \text{ V}$, $I_C = 1 \text{ mA}$	5	5.8	6.5	V
I_{CES}	$V_{GE} = 0 \text{ V}$, $V_{CE} = 1200 \text{ V}$, $T_j = 25^\circ\text{C}$	0.1	0.3		mA
C_{ies}	$V_{CE} = 25 \text{ V}$ $V_{GE} = 0 \text{ V}$	$f = 1 \text{ MHz}$	1.95		nF
C_{oes}		$f = 1 \text{ MHz}$	0.16		nF
C_{res}		$f = 1 \text{ MHz}$	0.12		nF
Q_G	$V_{GE} = -8 \text{ V} \dots +15 \text{ V}$		200		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		0		Ω
$t_{d(on)}$	$V_{CC} = 600 \text{ V}$	$T_j = 150^\circ\text{C}$	30		ns
t_r	$I_C = 35 \text{ A}$	$T_j = 150^\circ\text{C}$	35		ns
E_{on}	$R_{G on} = 18 \Omega$	$T_j = 150^\circ\text{C}$	4.3		mJ
$t_{d(off)}$	$R_{G off} = 18 \Omega$	$T_j = 150^\circ\text{C}$	300		ns
t_f		$T_j = 150^\circ\text{C}$	55		ns
E_{off}	$V_{GE} = +15/-15 \text{ V}$	$T_j = 150^\circ\text{C}$	3.25		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8 \text{ W/(mK)}$		1		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5 \text{ W/(mK)}$		0.82		K/W



NAB

SKiiP 24NAB12T4V1



MiniSKiiP® 2

SKiiP 24NAB12T4V1

Features

- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

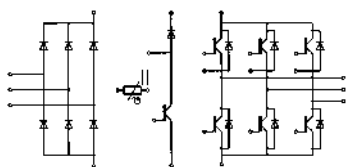
Typical Applications*

- Inverter up to 22 kVA
- Typical motor power 11 kW

Remarks

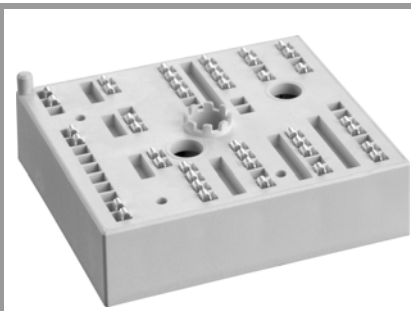
- Case temp. limited to $T_C = 125^\circ\text{C}$ max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Chopper - IGBT						
V _{CE(sat)}	I _C = 35 A	T _J = 25 °C		1.85	2.10	V
	V _{GE} = 15 V chipelevel	T _J = 150 °C		2.25	2.45	V
V _{CE0}	chipelevel	T _J = 25 °C		0.80	0.90	V
		T _J = 150 °C		0.70	0.80	V
r _{CE}	V _{GE} = 15 V	T _J = 25 °C		30	34	mΩ
	chipelevel	T _J = 150 °C		44	47	mΩ
V _{GE(th)}	V _{GE} = V _{CE} V, I _C = 1 mA		5	5.8	6.5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = 1200 V, T _J = 25 °C			0.1	0.3	mA
Q _G	V _{GE} = - 8 V...+ 15 V			200		nC
R _{Gint}	T _J = 25 °C			0		Ω
t _{d(on)}	V _{CC} = 600 V	T _J = 150 °C		30		ns
t _r	I _C = 35 A	T _J = 150 °C		35		ns
E _{on}	R _{G on} = 18 Ω	T _J = 150 °C		4.3		mJ
t _{d(off)}	R _{G off} = 18 Ω	T _J = 150 °C		300		ns
t _f		T _J = 150 °C		55		ns
E _{off}	V _{GE} = +15/-15 V	T _J = 150 °C		3.25		mJ
R _{th(j-s)}	per IGBT, λ _{paste} =0.8 W/(mK)			1		K/W
R _{th(j-s)}	per IGBT, λ _{paste} =2.5 W/(mK)			0.82		K/W
Inverse - Diode						
V _F = V _{EC}	I _F = 35 A	T _J = 25 °C		2.30	2.62	V
	V _{GE} = 0 V chipelevel	T _J = 150 °C		2.29	2.62	V
V _{F0}	chipelevel	T _J = 25 °C		1.30	1.50	V
		T _J = 150 °C		0.90	1.10	V
r _F	chipelevel	T _J = 25 °C		29	32	mΩ
		T _J = 150 °C		40	43	mΩ
I _{RRM}	I _F = 35 A	T _J = 150 °C		34		A
Q _{rr}	di/dt _{off} = 1250 A/μs	T _J = 150 °C		5.6		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 600 V	T _J = 150 °C		2.4		mJ
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(mK)			1.2		K/W
R _{th(j-s)}	per Diode, λ _{paste} =2.5 W/(mK)			1		K/W
Freewheeling - Diode						
V _F = V _{EC}	I _F = 35 A	T _J = 25 °C		2.30	2.62	V
	V _{GE} = 0 V chipelevel	T _J = 150 °C		2.29	2.62	V
V _{F0}	chipelevel	T _J = 25 °C		1.30	1.50	V
		T _J = 150 °C		0.90	1.10	V
r _F	chipelevel	T _J = 25 °C		29	32	mΩ
		T _J = 150 °C		40	43	mΩ
I _{RRM}	I _F = 35 A	T _J = 150 °C		34		A
Q _{rr}	di/dt _{off} = 1250 A/μs	T _J = 150 °C		5.6		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 600 V	T _J = 150 °C		2.4		mJ
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(mK)			1.2		K/W
R _{th(j-s)}	per Diode, λ _{paste} =2.5 W/(mK)			1		K/W



NAB

SKiiP 24NAB12T4V1



MiniSKiiP® 2

SKiiP 24NAB12T4V1

Features

- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

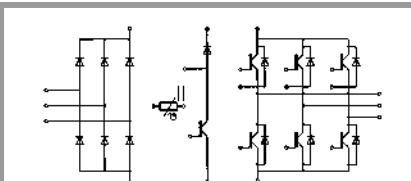
Typical Applications*

- Inverter up to 22 kVA
- Typical motor power 11 kW

Remarks

- Case temp. limited to $T_C = 125^\circ\text{C}$ max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)

Characteristics					
Symbol	Conditions		min.	typ.	max. Unit
Rectifier - Diode					
$V_F = V_{EC}$	$I_F = 13 \text{ A}$ $V_{GE} = 0 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$		1.00	1.21 V
		$T_j = 125^\circ\text{C}$		0.90	1.10 V
V_{F0}	chipelevel	$T_j = 25^\circ\text{C}$		0.88	0.98 V
		$T_j = 125^\circ\text{C}$		0.73	0.83 V
r_F	chipelevel	$T_j = 25^\circ\text{C}$		9.2	18 mΩ
		$T_j = 125^\circ\text{C}$		13	21 mΩ
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8 \text{ W/(mK)}$			1.25	K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5 \text{ W/(mK)}$			1.1	K/W
Module					
M_s	to heat sink		2		2.5 Nm
w				55	g
L_{CE}				-	nH
Temperature Sensor					
R_{100}	$T_r = 100^\circ\text{C}$			$1670 \pm 3\%$	Ω
$R(T)$	$R(T)=1000\Omega[1+A(T-25^\circ\text{C})+B(T-25^\circ\text{C})^2]$], $A = 7.635 \cdot 10^{-3} \text{ }^\circ\text{C}^{-1}$, $B = 1.731 \cdot 10^{-5} \text{ }^\circ\text{C}^{-2}$				



NAB

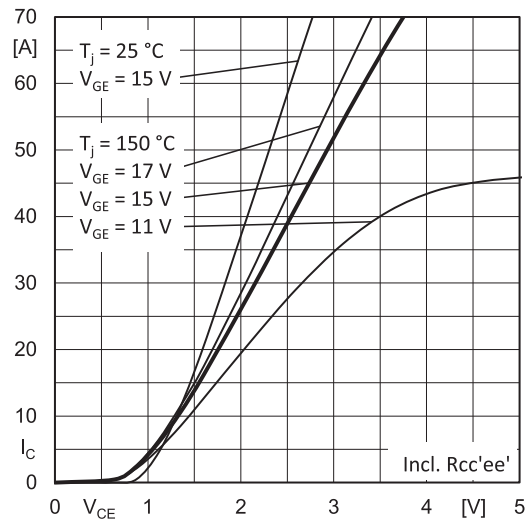


Fig. 1: Typ. output characteristic

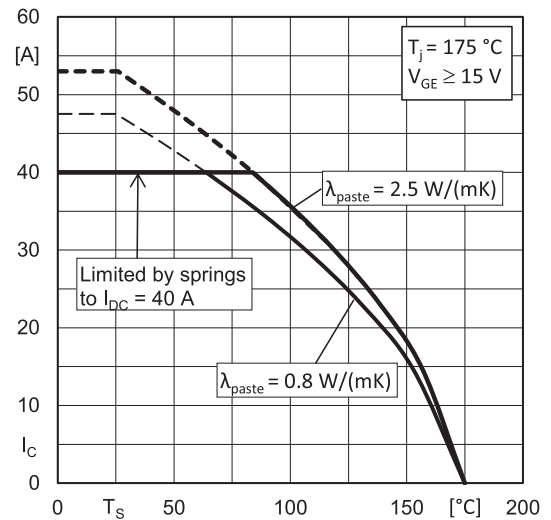


Fig. 2: Typ. rated current vs. temperature $I_C = f(T_S)$

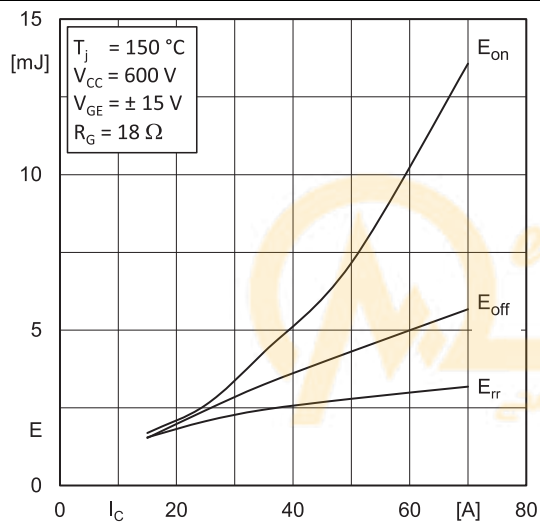


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

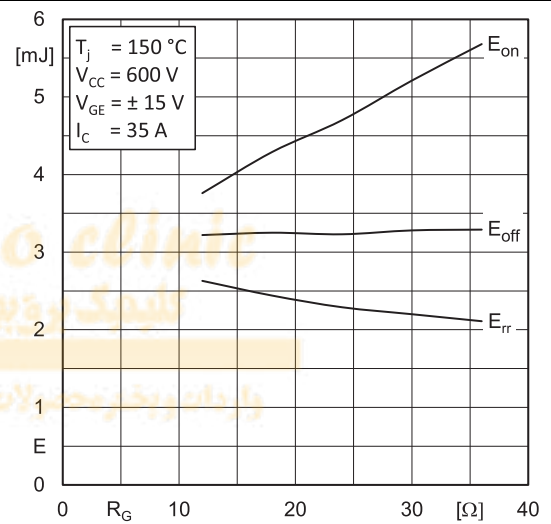


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

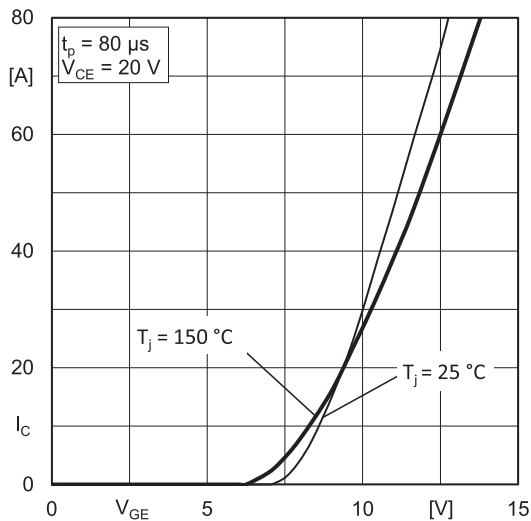


Fig. 5: Typ. transfer characteristic

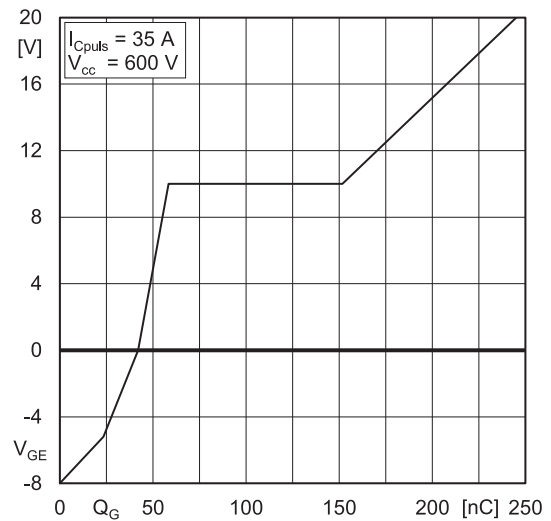
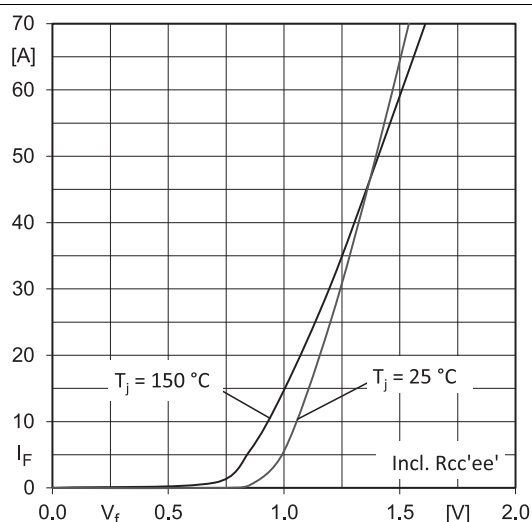
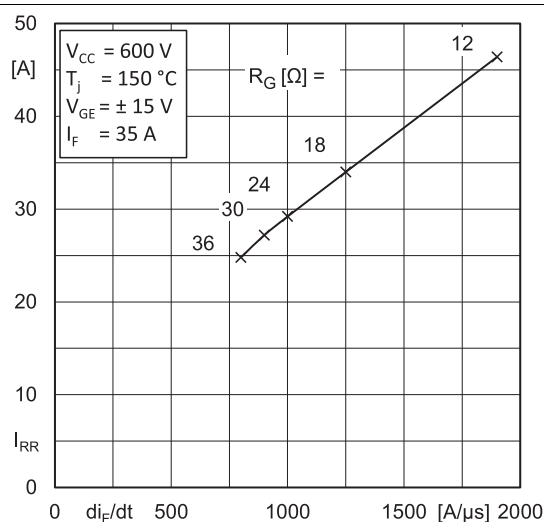
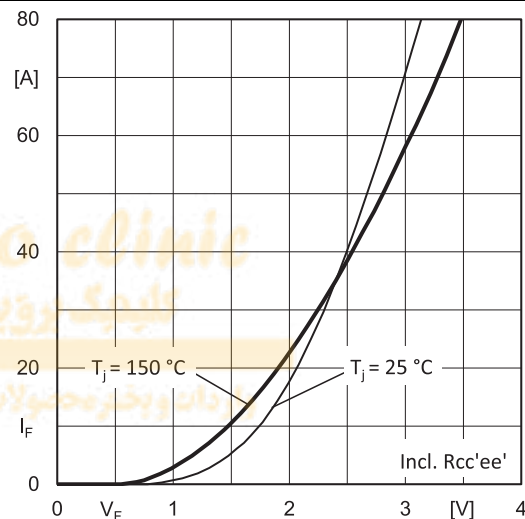
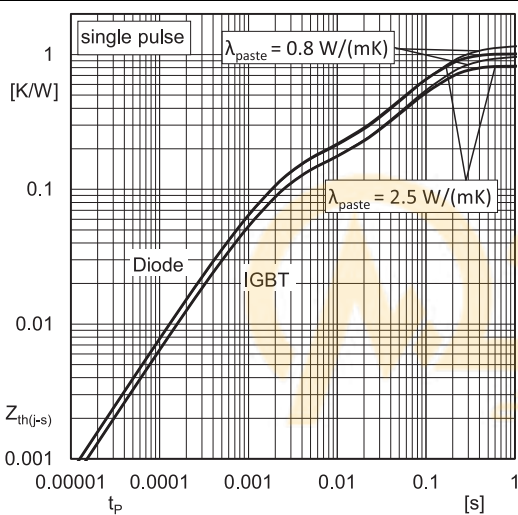
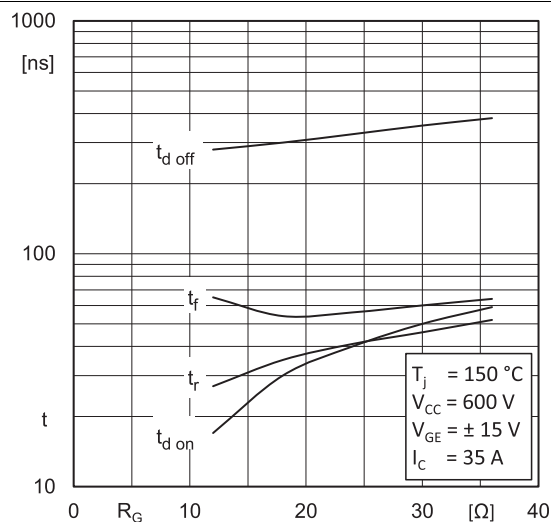
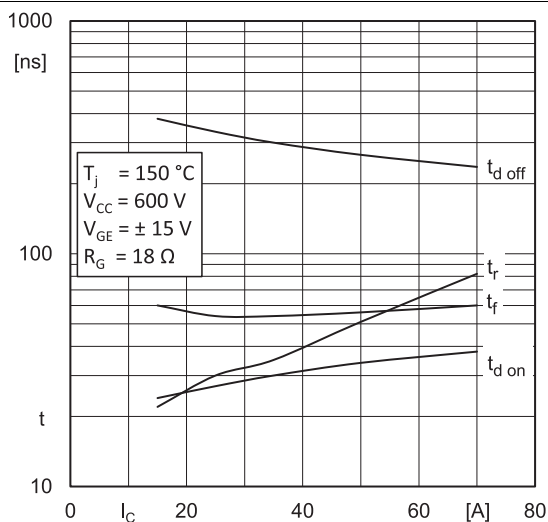
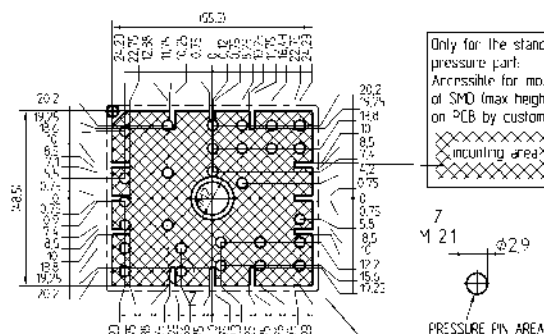


Fig. 6: Typ. gate charge characteristic

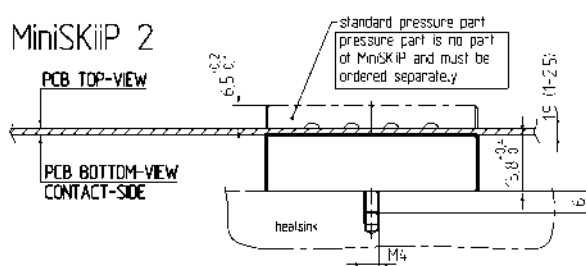


PCB
PCB TOP-VIEW

Only for the standard pressure part:
Accessible for mounting of SMD (max height 35) on PCB by customer!

Diagram showing a pressure fin area with dimensions 7, 21, and 2.9. The text "PRESSURE FIN AREA" is written below the diagram.

MiniSKiIP 2

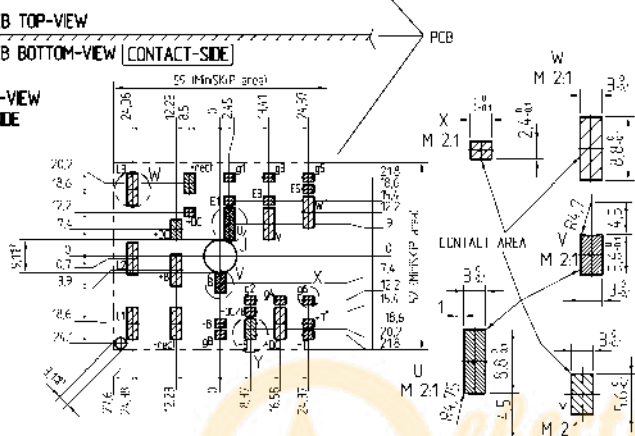


standard pressure part
pressure part is no part
of MiniSkiP and must be
ordered separately

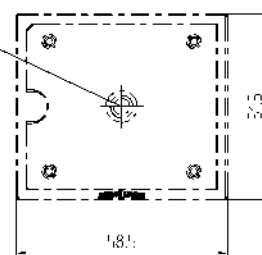
PCB TOP-VIEW
PCB BOTTOM-VIEW CONTACT-SIDE

PCB BOTTOM-VIEW
CONTACT-SIDE

24.36	55.44	55.44
32.22	32.22	32.22
8.5	8.5	8.5
0	0	0
2.45	2.45	2.45



For mounting please follow the assembly instruction

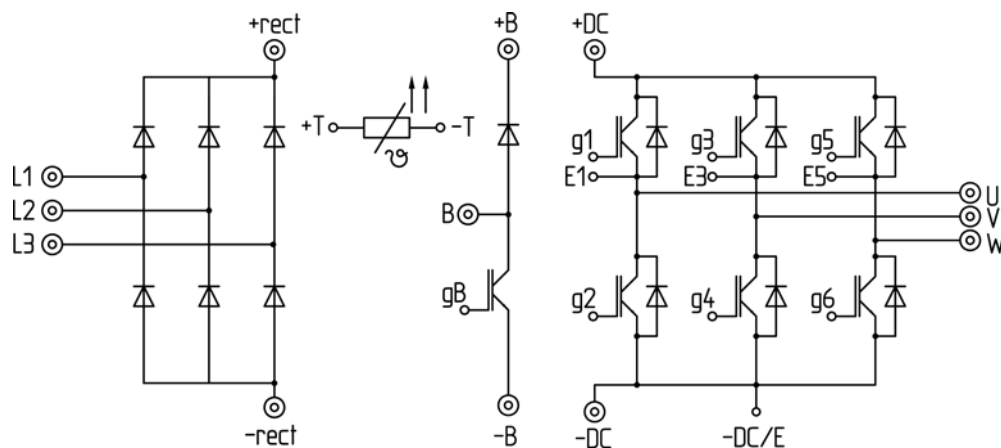


measure: mm
tolerance: ISO 2768-t

م. 2

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pinout, dimensions



- ⊙ power connector
- control connector

pinout

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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